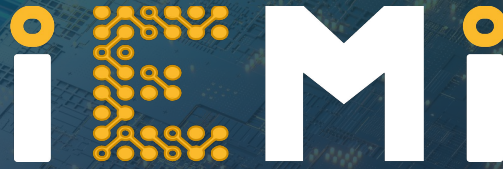




3<sup>rd</sup> Edition



Integrated Electronics  
Manufacturing & Interconnections

# "ADVANCED PACKAGING OF SEMICONDUCTOR"

PENANG, MALAYSIA  
JULY 24 - 25, 2024

## POST SHOW REPORT



Dr. Eu Poh Leng  
Senior Director  
External Packaging  
Chief Technology Officer  
NXP Semiconductors

Earl Lawrence S. Qua  
President  
Electronic Industries  
Association of Malaysia

Amruth Awasthi  
Vice President  
India Electronics & Semiconductor  
Association

Dr. Hari Narayanan  
CEO  
Penang High Performance  
Center

Agnon Akhavan  
CEO  
Penang Semiconductor  
Innovation Center

On Ho Ngai  
CEO  
Penang Semiconductor  
Innovation Center



**JULY 24, 2024**

**SETIA SPICE CONVENTION CENTRE, PENANG (MALAYSIA)**



**CO-LOCATED WITH**



## B2B MEETINGS

**200+** Meetings between Malaysian Companies and **29** International Delegates





**JULY 25, 2024**

**OLIVE TREE HOTEL , PENANG (MALAYSIA)**

## KEYNOTE ADDRESS

"What's New in Technology: Micro Trends Determining Electronics' Future", in his presentation, **Dr John Mitchell, President & CEO of IPC** emphasized number of micro trends affecting the electronics industry – computers everywhere, connected & smart everything, datafication, artificial intelligence, digital trust, 3D printing, nanotechnology, and new energy solutions. These trends have opened world of opportunities for the electronics industry, and IPC is committed to unlock the benefits for members and working to create an environment for embracing these trends, enabling members to stay ahead of the competition and continue to innovate and grow.



## FELICITATING PARTNER ORGANIZATIONS





## SPECIAL ADDRESS

### ADVANCED PACKAGING OF SEMICONDUCTOR: THE NEED TO BUILD AN INDUSTRIAL ECO SYSTEM



**Teng Chow Ooi,**  
Senior Director Program Office  
- Intel Corporation

**Takatoshi Ikeuchi,** Electronics R & D center  
- Resonac Corporation  
(Japan Semiconductor Packaging Consortium)

## PANEL DISCUSSION

### IMPORTANCE OF ADVANCED PACKAGING TECHNOLOGY @ SEMICONDUCTOR & ELECTRONICS INDUSTRY

The session Moderator: Dr. Bernard Lim. Chair-Elect, IEEE Malaysia & Vice President – Appscard Global Research & Innovation Centre



#### Panel Members

- **Dr. Eu Poh Leng**, Senior Director of External Package Innovation, Chief Technology Office - NXP Semiconductors
- **Sebastian Zheng**, Council Member - Association of Electronic Industries in Singapore
- **Earl Lawrence S. Qua**, President - Electronics Industries Association of Philippines
- **Anurag Awasthi**, Vice President - India Electronics & Semiconductor Association
- **Dr Hari Narayanan**, CEO - Penang Skills Development Centre
- **Ayman Ahmed**, CEO Pearl Semiconductor - Global Semiconductor Alliance, Egypt
- **Do Thi Thuy Huong**, Board Director - Vietnam Electronics Industries Association
- **Madhu Jambunathan**, Supply chain facilitator - Semiconductor Sector Service Bureau, Australia

IPC initiatives on Advanced Packaging of Semiconductors:  
[www.ipc.org/solutions/ipc-advanced-packaging-technology](http://www.ipc.org/solutions/ipc-advanced-packaging-technology)



## MOU SIGNING



**Selangor Human Resource Development Center**



**Penang Skill Development Center**

Malaysia stands as a prominent global player in producing electronic & semiconductor products. Domestic & international companies are accelerating the electronics & semiconductor industries. IPC signed MoU with Skill Development Organizations for growth of skill workforce in electronics manufacturing. Upskilling & reskilling the existing technical workforce with international level skills and competencies through industry endorsed global standards will be the key deliverables of the initiative.

## HAND SOLDERING REWORK COMPETITION



**Registration Received: 80+**

**Total Candidates played during July 24-26: 36**

**WINNER**

**Pubalan Sivasangkar, Cytron Technologies Sdn Bhd**

**RUNNER UP**

**Hasrol Mizam Bin Hassan & Norishah Binti Othman, Jabil Circuit Sdn Bhd**



# EXHIBITORS



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**JBC**  
The Soldering Co.



**QDOS**



Through IEMI 24, it was an honor to showcase the capabilities of the Philippine electronics sector in the South Asia region. The event offered an excellent opportunity to network, establish strategic alliances, and connect with potential partners to enhance the business capabilities and market reach of the Philippine delegates.



**Katrina C. Lachica**  
Trade-Industry Development Specialist  
Department of Trade & Industry –  
Export Marketing Bureau  
Government of Philippines

## IPC Contact:

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